03 February 2004

L Number	Hits	Search Text	DB	Time stamp
-	9449	205/\$.ccls. and (microelectronic or circuit or wafer	USPAT;	2004/02/02
		or electronic or semiconductor)	US-PGPUB;	11:36
			EPO; JPO;	
			DERWENT;	
		·	IBM_TDB	
-	5847	(205/\$.ccls. and (microelectronic or circuit or wafer	USPAT;	2004/02/02
		or electronic or semiconductor)) and (via or aperture	US-PGPUB;	11:37
		or throughhole or hole or opening or trench)	EPO; JPO;	
		, ,	DERWENT;	
			IBM_TDB	
	1	045245.apn.	USPAT;	2004/02/02
	•	·	US-PGPUB;	14:16
			EPO; JPO;	
			DERWENT;	
		·	IBM_TDB	
-	2	6197181.pn.	USPAT;	2004/02/02
			US-PGPUB;	14:19
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2	6113771.pn.	USPAT;	2004/02/02
	,		US-PGPUB;	14:19
	•		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	2	6375731.pn.	USPAT;	2004/02/03
		•	US-PGPUB;	10:07
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	3231	.los/81,82,84,118,123,125,126,183,205,210,219,291.ccl	s.USPAT;	2004/02/03
		·	US-PGPUB;	10:08
			EPO; JPO;	
		·	DERWENT;	
			IBW_TDB	
-	3300	205/81,82,84,118,123,125,126,183,205,210,215,219,29		2004/02/03
			US-PGPUB;	10:08
		•	EPO; JPO;	
			DERWENT;	
			IBW_TDB	
-	44	((205/\$.ccls. and (microelectronic or circuit or wafer	USPAT;	2004/02/03
		or electronic or semiconductor)) and (via or aperture	US-PGPUB;	10:09
1		or throughhole or hole or opening or trench)) and	EPO; JPO;	
		((test\$5 or check\$5 or analy\$7) with (void\$5 or	DERWENT;	
		discontin\$))	IBW_TDB	

	0	(205/81,82,84,118,123,125,126,183,205,210,215,219,29	1.66BAT;	2004/02/03
		and (microelectronic or circuit or wafer or electronic	US-PGPUB;	10:09
		or semiconductor) and (via or aperture or throughhole	EPO; JPO;	
		or hole or opening or trench) and ((test\$5 or	DERWENT;	ĺ
1		check\$5 or analy\$7) with (void\$5 or discontin\$)))	IBM_TDB	
		not (((205/\$.ccls. and (microelectronic or circuit or		
		wafer or electronic or semiconductor)) and (via or		
		aperture or throughhole or hole or opening or		
		trench)) and ((test\$5 or check\$5 or analy\$7) with		
	13	205d\$5,82,8i4d8t12\$)))25,126,183,205,210,215,219,291	.dd&PAT	2004/02/03
		and (microelectronic or circuit or wafer or electronic	US-PGPUB;	10:09
		or semiconductor) and (via or aperture or throughhole	EPO; JPO;	
		or hole or opening or trench) and ((test\$5 or	DERWENT;	
	·	check\$5 or analy\$7) with (void\$5 or discontin\$))	IBM_TDB	